



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Elite t660 Thin Client

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB <input checked="" type="checkbox"/> Solid state drive (SSD) PCB <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB <input checked="" type="checkbox"/> External Keyboard (KB) <input checked="" type="checkbox"/> External Mouse <input type="checkbox"/> Others: _____	5
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input type="checkbox"/> Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	PH0X50 screw driver
Screwdriver	T15 screw driver
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.



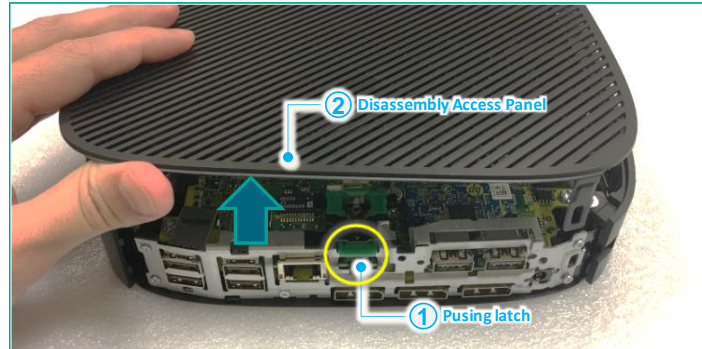

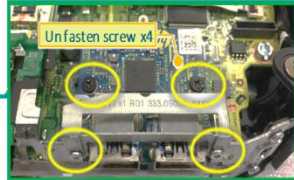

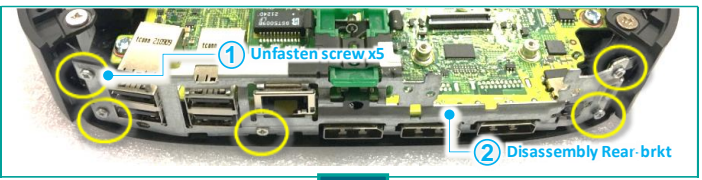






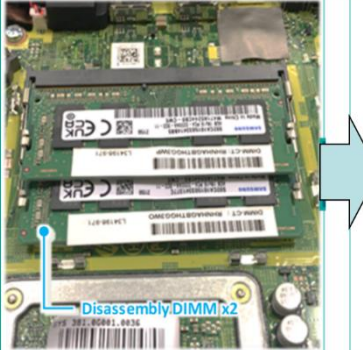
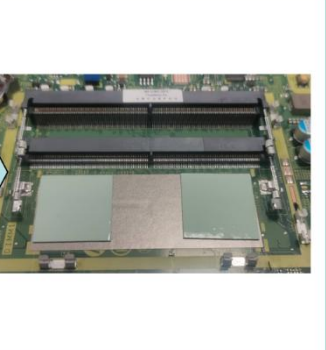
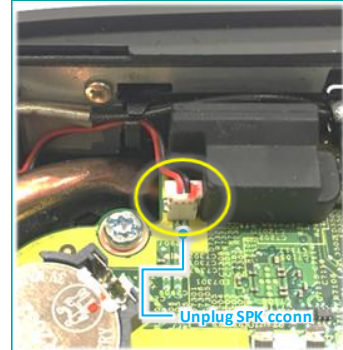
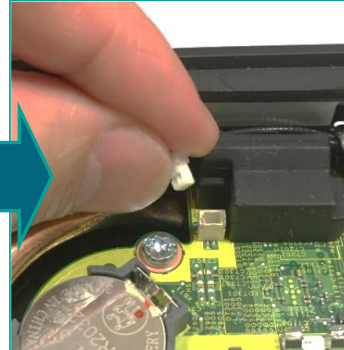
1. Remove Rear Cover
2. Remove access panel
3. Remove "+"M2 screws of option kit and option board
4. Remove "+"M2 screws of Rear-brkt
5. Remove T8-SSD screw and module
6. Remove shielding can
7. Remove DIMM
8. Remove speaker conn
9. Unfasten T15-M3 screws and disassembly MB
10. Remove speaker
11. Unfasten "+" M2 screws and internal antenna
12. Unfasten "+" M3 screws and internal antenna
13. Unfasten "+" M2 screws
14. Remove VESA cover by hand
15. Remove Bend cover by hand

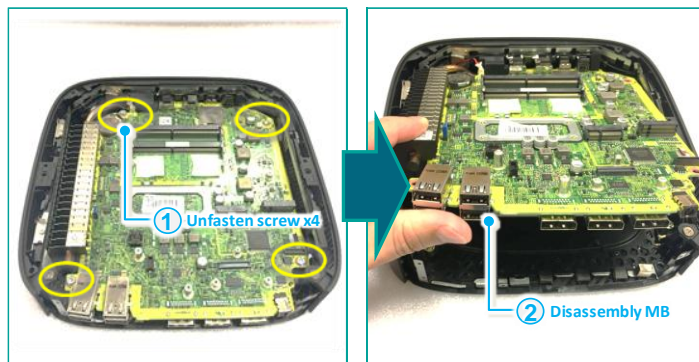
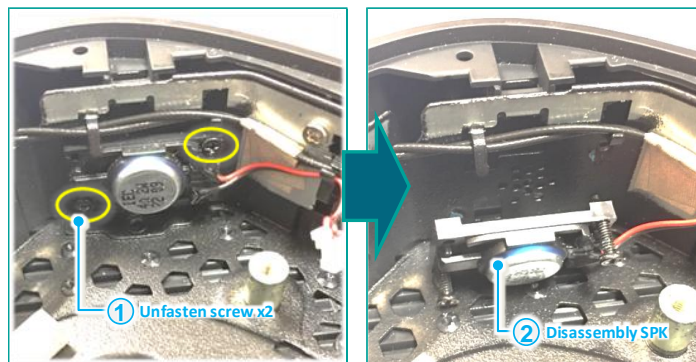
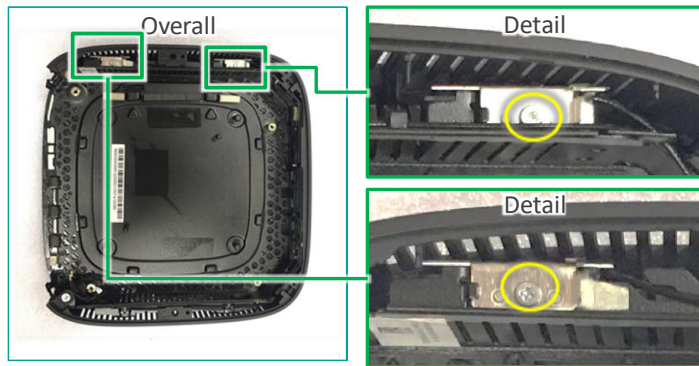
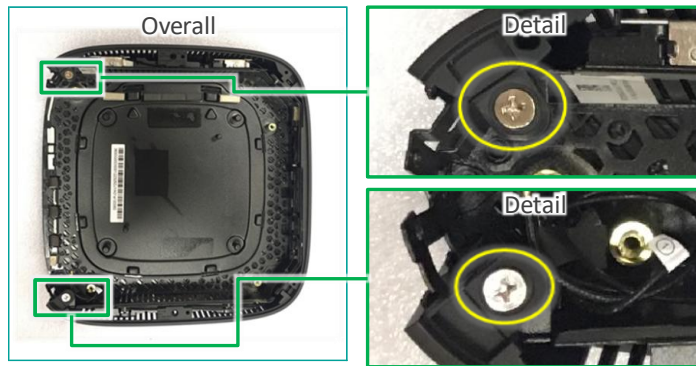
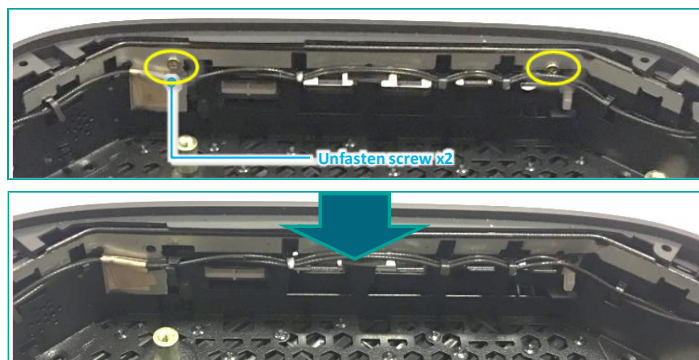
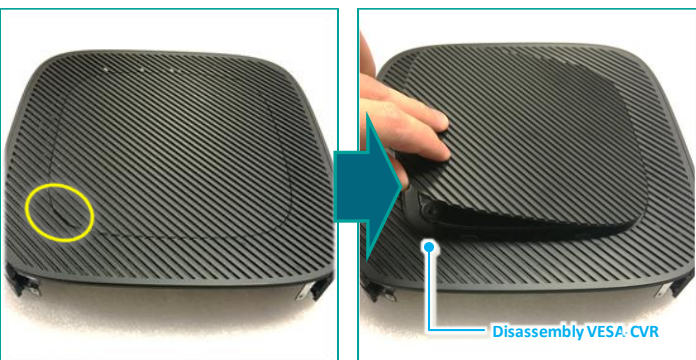
NOTE - For disassembly instructions of the external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the links below:

- [Generic External Power Supply \(EPS\)](#)
- [Generic Keyboard](#)
- [Generic Mouse](#)
- [Generic cables and cords](#)

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](#)

STEP 1. Remove Rear Cover	STEP 2. Remove access panel
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 <p>Releasing latch</p> 	 <p>② Disassembly Access Panel</p> <p>① Pushing latch</p>
<p>STEP 3. Remove “+”M2 screws of option kit and option board</p>	<p>STEP 4. Remove “+”M2 screws of Rear-brkt</p>
 <p>Over all</p>  <p>Unfasten screw x4</p> 	 <p>① Unfasten screw x5</p> <p>② Disassembly Rear-brkt</p> 
<p>STEP 5. Remove T8-SSD screw and module</p>	<p>STEP 6. Remove shielding can</p>
  <p>① Unfasten screw</p>  <p>② Disassembly module</p>	  <p>Disassembly Shielding can</p>
<p>STEP 7. Remove DIMM</p>	<p>STEP 8. Remove speaker conn</p>
 <p>Disassembly DIMM x2</p> 	 <p>Unplug SPK cconn</p> 

STEP 9. Unfasten T15-M3 screws and disassembly MB**STEP 10. Remove speaker****STEP 11. Unfasten “+” M2 screws and internal antenna****STEP 12. Unfasten “+” M3 screws and internal antenna****STEP 13. Unfasten “+” M2 screws****STEP 14. Remove VESA cover by hand****STEP 15. Remove Bend cover by hand**

